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- Members of the Texas Instruments
   Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- A-Port Outputs Have Equivalent 22-Ω
   Series Resistors, So No External Resistors
   Are Required
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   < 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- I<sub>off</sub> and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### SN54LVTH162245 . . . WD PACKAGE SN74LVTH162245 . . . DGG OR DL PACKAGE (TOP VIEW)

				1
1DIR [	1	$\cup$	48	10E
1B1 [	2		47	] 1A1
1B2 [	3		46	] 1A2
GND [	4		45	GND
1B3 [			44	] 1A3
1B4 [	6		43	] 1A4
V <sub>CC</sub> [			42	] v <sub>cc</sub>
1B5			41	1A5
1B6			40	1A6
GND [			39	GND
1B7	11		38	1A7
1B8			37	] 1A8
2B1	13		36	2A1
2B2			35	2A2
GND [				GND
2B3				2A3
2B4	17		32	2A4
V <sub>CC</sub>			31	] v <sub>cc</sub>
2B5 [	19			2A5
2B6				2A6
GND [			28	GND
2B7			27	2A7
2B8			26	2 <u>A8</u>
2DIR [	24		25	2 <u>0E</u>
	-		_	,

#### description

The 'LVTH162245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V<sub>CC</sub> operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.



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#### description (continued)

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 22- $\Omega$  series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When  $V_{CC}$  is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

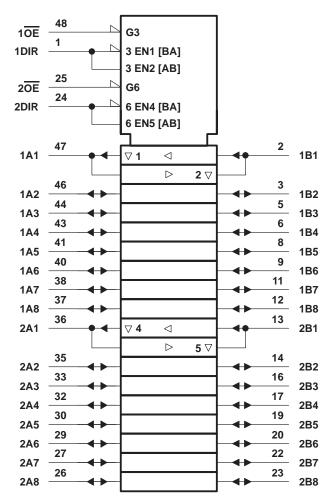
The SN54LVTH162245 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74LVTH162245 is characterized for operation from  $-40^{\circ}$ C to 85°C.

## FUNCTION TABLE (each 8-bit section)

	•	·							
INPUTS		OPERATION							
OE	DIR	OPERATION							
L	L	B data to A bus							
L	Н	A data to B bus							
н	X	Isolation							

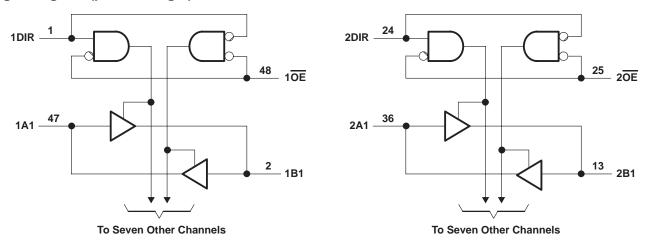


## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, $V_{CC}$
Voltage range applied to any output in the high-impedance
or power-off state, V <sub>O</sub> (see Note 1)
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)
Current into any output in the low state, IO: SN54LVTH162245 (B port)
SN74LVTH162245 (B port)
A port
Current into any output in the high state, I <sub>O</sub> (see Note 2): SN54LVTH162245 (B port)
SN74LVTH162245 (B port) 64 mA
A port 30 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)
Output clamp current, $I_{OK}$ ( $V_O < 0$ )
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package
DL package 94°C/W
Storage temperature range, T <sub>stg</sub> 65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  - 3. The package thermal impedance is calculated in accordance with JESD 51.

#### recommended operating conditions (see Note 4)

				162245	SN74LVTH	UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage				2		V
V <sub>IL</sub>	Low-level input voltage		0.8		8.0	V	
VI	Input voltage		5.5		5.5	V	
lou	High-level output current	A port		-12		-12	mA
ІОН	riigh-level output current	B port		-24		-32	IIIA
La. Law lavel out	Low-level output current	A port		12		12	mA
IOL	Low-level output current	B port		48		64	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
T <sub>A</sub>	Operating free-air temperature			125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54	LVTH16	2245	SN74LVTH162245			UNIT				
				MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNII				
VIK		$V_{CC} = 2.7 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2			-1.2	V				
VOH	A port	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -100  \mu A$	VCC-0	V <sub>CC</sub> -0.2			V <sub>CC</sub> -0.2						
	A poit	$V_{CC} = 3 V$	$I_{OH} = -12 \text{ mA}$	2			2							
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0	V <sub>CC</sub> -0	V <sub>CC</sub> -0.2								
	B port	$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V				
	D port	VCC = 3 V	$I_{OH} = -24 \text{ mA}$	2										
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2							
	A port	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I <sub>OL</sub> = 100 μA			0.2			0.2					
	Apolt	$V_{CC} = 3 V$	I <sub>OL</sub> = 12 mA			0.8			0.8					
		V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 100 μA			0.2			0.2					
VOL		VCC = 2.7 V	I <sub>OL</sub> = 24 mA			0.5		0.5						
VOL	B port		I <sub>OL</sub> = 16 mA			0.4	0.4			V				
	B poit	V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 32 mA		0.5			0.5						
			I <sub>OL</sub> = 48 mA			0.55				]				
			I <sub>OL</sub> = 64 mA						0.55					
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1					
		$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V <sub>I</sub> = 5.5 V			10				μΑ				
lį	A or B ports‡	V <sub>CC</sub> = 3.6 V	V <sub>I</sub> = 5.5 V	20										
			$V_I = V_{CC}$		5			5						
			V <sub>I</sub> = 0	-10			-10							
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$						±100	μΑ				
		VCC = 3 V	$V_1 = 0.8 \text{ V}$ 75											
l(hold)	A or B ports		V <sub>I</sub> = 2 V	-75			-75	–75 μA						
ri(noia)	/ or B ports	V <sub>CC</sub> = 3.6 √§,	V <sub>I</sub> = 0 to 3.6 V						500 -750	μν				
lozpu		$\frac{\text{V}_{\text{C}}\text{C}}{\text{OE}} = 0 \text{ to } 1.5 \text{ V, V}_{\text{O}} = 0$	0.5 V to 3 V,			±100*			±100	μΑ				
l <sub>OZPD</sub>		$\frac{V_{CC}}{OE}$ = 1.5 V to 0, $V_{O}$ = OE = don't care	0.5 V to 3 V,			±100*			±100	μΑ				
	V <sub>CC</sub> = 3.6 V,	Outputs high	1	0.				0.19						
Icc		$I_{O} = 0$ ,	Outputs low		5		5			mA				
		$V_I = V_{CC}$ or GND	Outputs disabled	1	0.19		0.19							
ΔI <sub>CC</sub> ¶		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ , One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND				0.3			0.2	mA				
Ci		V <sub>I</sub> = 3 V or 0		1	4			4		pF				
		V <sub>O</sub> = 3 V or 0			10			10						
C <sub>io</sub>		V <sub>O</sub> = 3 V or 0			10			10		pF				

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.



<sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

‡ Unused pins at  $V_{CC}$  or GND.

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

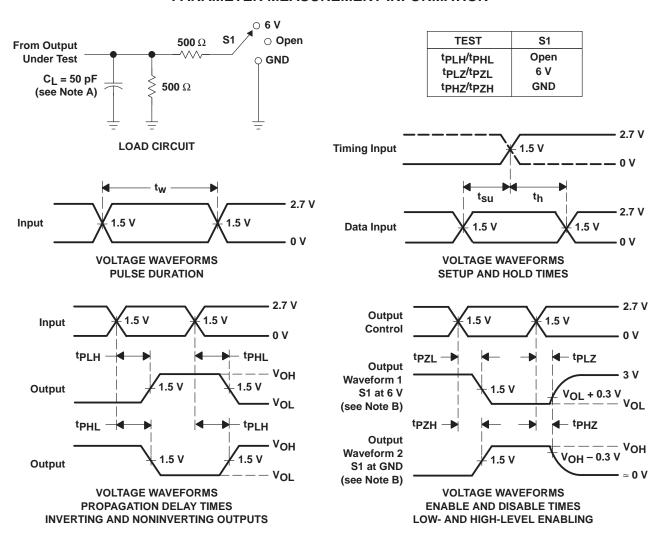
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# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

			S	N54LVT	H162245	5		SN74	LVTH16	2245		
PARAMETER	FROM (INPUT)		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	
t <sub>PLH</sub>	Α	В	1	3.5		4	1	2.3	3.3		3.7	ns
t <sub>PHL</sub>	A	В	1	3.5		3.9	1	2.2	3.3		3.5	113
t <sub>PLH</sub>	В	А	1	4.3		5.3	1	2.8	4		4.6	ns
t <sub>PHL</sub>		A	1	4.2		4.5	1	2.5	3.4		3.6	115
<sup>t</sup> PZH	ŌĒ	В	1	4.8		5.9	1	2.8	4.6		5.4	ns
t <sub>PZL</sub>		В	1	4.8		5.5	1	3	4.6		5.2	115
<sup>t</sup> PZH		А	1	5.5		7.2	1	3.3	5.3		6.3	ns
tPZL	ŌĒ	A	1	5.4		6.4	1	3.3	5.1		5.8	115
t <sub>PHZ</sub>	ŌĒ	В	1.5	5.5		5.8	1.5	3.8	5.2		5.5	ns
t <sub>PLZ</sub>		В	1.5	5.5		5.8	1.5	3.5	5.1		5.4	115
t <sub>PHZ</sub>	ŌĒ	А	1.5	5.8		6.5	1.5	4	5.6		5.9	ns
t <sub>PLZ</sub>		^	1.2	6.3		6.3	1.5	3.8	5.5		5.5	115
tsk(o)									0.5			ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ ,  $t_{f} \leq$  2.5 ns,  $t_{f} \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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